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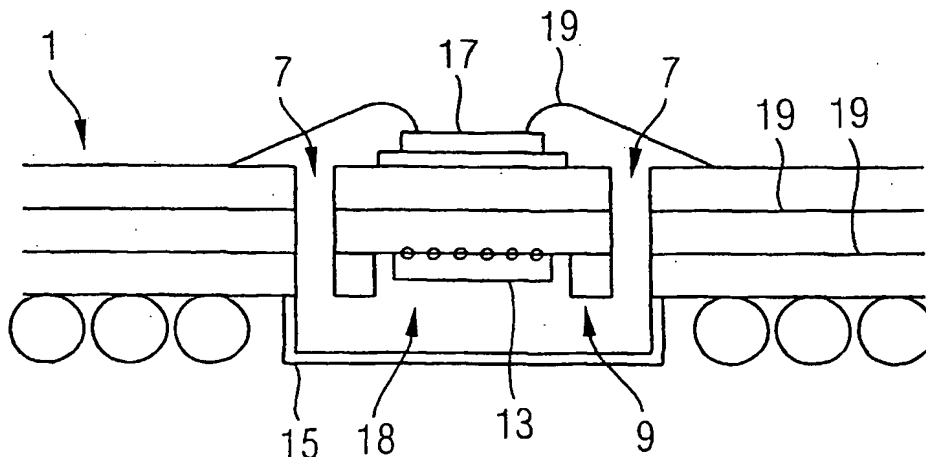
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(54) Title: METHOD OF PACKAGING INTEGRATED CIRCUITS, AND INTEGRATED CIRCUIT PACKAGES PRODUCED BY THE METHOD



(57) Abstract: A method of packaging integrated circuits is proposed in which two integrated circuits 13, 17 are provided in register on opposite sides of a single substrate 1. Electrical contacts on the each of the integrated circuits 13, 17 are electrically connected to electrical conductors of the substrate 1. One of the integrated circuits 17 may be wire bonded to the substrate, while the other is a flip-chip 13. Holes 7 are provided through the substrate 1 so that in a moulding operation a single resin body 21 may be formed encasing both of the integrated circuits 13, 17 by applying resin only to an upper side of the substrate 1 and allowing the resin to flow to the other side of the substrate 1 into a volume defined by a box 15.



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